162162

G00002

ABSTRACT OF THE DISCLOSURE

SEMICONDUCTOR CHIP PACKAGE AND METHOD OF MANUFACTURE

A semiconductor chip package and method of making the same. A first chip unit includes a first substrate and a first IC chip electrically connected to the first substrate. A second chip unit includes a second substrate and a second IC chip electronically connected to the second substrate. An adhesive material is provided on a surface of the first IC chip and the second chip unit is mounted onto the surface of the first chip unit including the adhesive material so that at least a portion of the second structure is encapsulated by the adhesive material, thereby providing some encapsulation in the same step as mounting. The first chip unit and the second chip unit may be separated by a spacer which may also provide an electrical connection.

Figure 6